Building the Adaptable, Intelligent World



Automotive Applications for Machine Learning

Paul Zoratti March 2019



Outline

>Xilinx in Automotive

>ML in Automotive Applications

- Internal Camera
- » Forward Camera
- >> Central Modules

> DFX (Dynamic Function Exchange) Concept





Xilinx in Automotive



Xilinx Automotive Solutions and Products

Automotive Solutions



Automated / Autonomous Driving (AD)

Next decade of growth as the market drives adoption of conditional automated driving features up through full autonomous vehicles. Includes key new technologies such as Deep Learning paired with traditional Discriminatory Object Detection.

Advanced Driver Assistance Systems (ADAS)

Currently driven by regional NCAP initiatives pushing collision avoidance, pedestrian, bicycle/motorcycle, vehicle, sign detection and tracking features.

In Cabin Driver Information

IVI and DI are converging with sharing of information and larger. HMI trends like Heads-Up Displays (HUD), Augmented Reality, eMirror - and Gesture Recognition are changing the way Drivers and Passengers interact with the vehicle. Secure Vehicle to Infrastructure/Vehicle (V2X) networks required.

Electrification

Electrification will provide new opportunities in Motor Control, charging systems, etc. Xilinx can leverage existing industrial motor control heritage to address these applications







ADAS and AD Focus Applications



Xilinx Automotive Devices





Xilinx Automotive (XA) Silicon Roadmap



Xilinx All Programmable SoC and MPSoC A Game Changing Technology in Automotive





SoC: System on Chip MPSoC: Multi-Processor System on Chip

Field Programmable Gate Array Based SoC's **Block RAMs** SysMon / ADCs Amilication Processi NEON" Good ASH Carbon - Al **Rooting Point Unit** Menangement Management Unit 1393 HGachy with Factly 1798 D-Gasto with ECC I/O Blocks 500 GC 03/5MM (ME12 G-AVTC) Processing 101-104 1011 **System** 114.2.3 Ca feel 19.00 Seal-Time Processing Unit. Vector Flooting Paint line Deal All Carbo "-F Nerwry Protectio 118-36-1020 129/8-1-Carche 139/8-2-Carche w/8-1021 with LLL with LDL in the second **Configurable Logic Blocks DSP Slices**

Flexibility and Performance

What is an FPGA?

Field Programmable Gate Array Based SoC's



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- Common Processor Peripherals (e.g. CAN / CAN-FD)



 Application Focused Connectivity (e.g. MIPI CSI-2 Controller and D-PHY)



> Inference DNN Processing Engines



> MicroBlaze 32-bit Soft Processor



Highly Parallelized and Customized DSP Acceleration (e.g. FFT)



> Unique, Differentiating User-Defined Functions or Pipelines of Functions



Zynq® UltraScale+™ MPSoC

Heterogeneous Multi-Processing at the Heart of the System



> PS Processing Units

- Applications Processor Unit (APU) = A53 Complex
- Real-Time Processing Unit (RPU) = R5 Complex
- Graphic Processing Unit (GPU) = Mali-400MP Complex
- Configuration Security Unit (CSU): Configuration & Security
- Platform Management Unit (PMU): Power & Safety

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XA Zynq UltraScale+ MPSoC – Smarter Control & Vision

Scalable platform offers easy migration between devices

	XA Zynq® UltraScale+™ MPSoC		Smarter Control & Vision			
	Dev	ices	ZU2EG	ZU3EG	ZU4EV	ZU5EV
Processing System	Application Processor Core		Quad ARM® Cortex™-A53 MPCore™ up to 1.2 GHz L1 Cache 32 KB I (w/ Parity) / D (w/ ECC), L2 Cache 1 MB (w/ ECC), on-chip Memory 256 KB (w/ ECC)			
	Real-Time Processor Core		Dual ARM® Cortex™-R5 MPCore™ up to 500 MHz L1 Cache 32 KB I (w/ Parity) / D (w/ ECC), L2 Cache 1 MB (w/ ECC), Tightly Coupled Memory 128 KB (w/ ECC)			
	GPU		Mali™-400, 600 MHz, 64 KB L2 Cache (w/ ECC)			
	External Memory Support		DDR3, DDR3L, LPDDR3, DDR4, LPDDR4, 2x QSPI, NAND (DDR Controller w/ ECC in all modes)			
	Peripherals		2x USB 2.0/3.0 (OTG), SATA 3.0, DisplayPort, 4x Tri-mode Gigabit Ethernet, PCIe® Gen2x4, 2x SD/SDIO, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO			
Programmable Logic	System Logic Cells (K)		103	154	192	256
	Block RAM (Mb)		5.3	7.6	4.5	5.1
	UltraRAM (Mb)		-	-	14	18
	DSP Slices		240	360	728	1056
	PCI Express® Gen 4		-	-	2	2
	Video Codec Unit		-	-	1	1
Package	Footprint	Dimensions	PS I/O, 3.3V HD I/O , 1.8V HP I/Os, PS-GTR 6 Gb/s, GTH 12.5Gb/s, GTY 33 Gb/s			
	SBVA484	19 mm @ 0.8	170, 24, 52 4,0,0	170, 24, 52 4,0,0		
	SFVA625	21 mm @ 0.8	170,24,156 4,0,0	170,24,156 4,0,0		
	SFVC784	23 mm @ 0.8	214,96,156 4,0,0	214,96,156 4,0,0	214,96,156 4,4,0	214,96,156 4,4,0

Partitioning Functionality in a Xilinx Automotive Device





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Xilinx Automotive Applications Leveraging AI/ML Processing

- Interior Cabin Sensing

- Forward Camera

- Central ADAS/AD Modules



Innovating In-Cabin AI Sensing

Jun. 26, 2018

DAIMLER



> Strategic Collaboration Announcement: Daimler Selects Xilinx for Al-based Auto Applications

- * "Xilinx is providing technology that will enable us to deliver very low latency and powerefficient solutions for vehicles that must operate in thermally constrained environments. We have been very impressed by Xilinx's heritage and selected the company as a trusted partner for our future products."
 - Georges Massing, Director, Daimler AG
- The system will be powered by a Xilinx automotive platform consisting of system-on-a-chip (SoC) devices and AI acceleration software. Mercedes-Benz will productize Xilinx's AI processor technology, enabling the most efficient execution of their neural networks.



Jan. 11, 2019

> MBUX Interior Assistant in Mercedes Benz GLE & CLA

- Interior Assist: AI-based gesture input system, powered by Zynq[®] UltraScale+[™] MPSoC
- * "Recognizes the occupants' natural movements so the vehicle can predict driver and passenger needs"
- The interior assist on GLE and CLA both using Zynq[®] UltraScale+[™] MPSoC, using a single camera



Automotive Forward Camera Evolution

Xilinx Deployed in Production Systems for first 3 Generations and targets NCAP2022 with Next Generation of Devices



Zynq 7000 Forward Looking Camera LDW + FCW / AEB – CV-based







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Zynq 7000 Forward Looking Camera LDW + FCW / AEB – AI-based





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Automated Driving System Functional Diagram



Some Sense & Detect Processing may be done in Main ADAS/AD Compute Module

AD Central Module Processing Element Architecture



- > A centralized AD processing module is commonly comprised of a heterogeneous set of processing element types:
 - >> Data Aggregator, Pre-Processor and Distributor
 - >> High Performance Compute Processor(s)
 - >> Computational Accelerators
 - Safety Processor(s)

AD ECU Architecture



Multi-camera Central Module Al Processing in XA







> AI / ML being broadly adopted into a variety of Automotive Applications

- Xilinx Automotive devices offer unique advantages in ML inference (e.g. DAPD integration, power, HW programmability for next generation innovations, etc.)
- Dynamic Function Exchange is a unique capability which efficiently enables bundles of mutually exclusive features in a minimized piece of silicon area
- > Xilinx Automotive team is eager to discuss your application with you.



Building the Adaptable, Intelligent World

